


REVISION HISTORY				
ECO	REV	DESCRIPTION	APP. ENG.	DATE
-	3	PRODUCTION	MARK T.	05-03-18

## NOTES: UNLESS OTHERWISE SPECIFIED

1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
2. ASSEMBLY PROCESS SHALL INCLUDE: REFLOW SOLDER TOP SIDE SMD. MAXIMUM SOLDER TEMPERATURE IS 240 DEGREES CELSIUS.
3. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS. LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER. MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
4. INSTALL SHUNTS AS SHOWN.
5. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
6. DO NOT APPLY ANY KIND OF ASSEMBLY STAMP OR QA STAMP TO ANY BOARD.
7. THERE ARE 2 ASSEMBLY TYPES, -A AND -B, ON THIS DESIGN. SEE BILL OF MATERIALS FOR MORE DETAILS.

APPROVALS		 1630 MCCARTHY BLVD MILPITAS, CA 95035 PH: (408)432-1900 www.analog.com ADI CONFIDENTIAL- FOR CUSTOMER USE ONLY		
PCB DES.	KIM T.			
APP ENG.	MARK T.			
		TITLE: TOP ASSEMBLY DRAWING		
		ARDUINO FORM FACTOR TO SDP/QUIKEVAL/PMOD ADAPTER		
		SIZE N/A	IC NO. DEMO CIRCUIT 2741A	REV. 3
SCALE = NONE		FILENAME: DC2741A-3.PCB		SHT 1 OF 2